PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6849208

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shih-Ping Lee	07/26/2021
Tse-Hsien Wu	07/27/2021
Pin-Chieh Huang	07/29/2021
Yu-Hsiang Chien	07/28/2021
Yeh-Yu Chiang	07/27/2021

RECEIVING PARTY DATA

Name:	Powerchip Semiconductor Manufacturing Corporation
Street Address:	NO.18, LI-HSIN RD. 1, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17394372

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU

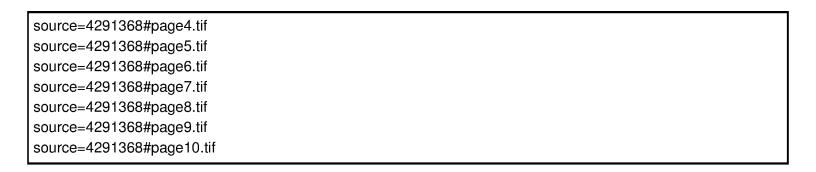
Address Line 1: 5F., NO.389, FUHE RD., YONGHE DIST.,

Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	PSMP0011USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	08/04/2021

Total Attachments: 10 source=4291368#page1.tif source=4291368#page2.tif source=4291368#page3.tif

PATENT 506802389 REEL: 057084 FRAME: 0585



PATENT REEL: 057084 FRAME: 0586

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

THROUGH SILICON VIA AND METHOD OF MANUFACTURING THE SAME

As the below named inventor, I here This declaration is directed to:			
☑ The attached application, or			
☐ United States application nu	mber	filed on	, or
☐ PCT international application	n number	filed on	
The above-identified application was	made or authorized to be made b	y me.	
I believe that I am the original invent application.	or or an original joint inventor of a	claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr			
In consideration of the payment by	Powerchip Semiconductor Manufacturing Corporation		ddress of
NO.18, LI-HSIN RD. 1, HSINCH	IU SCIENCE PARK, HSINCH	IU 300, Taiwan, R.O.	C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		O), the receipt of which is	hereby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applical invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements wh tion and, in and to, all Letters Pate any continuations, continuation-ir	nich are disclosed in the ent to be obtained for said n-part, divisions, renewals	l S,
I hereby covenant that no assignmer entered into which would conflict with		ce has been or will be ma	de or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent and le stify as to the same in any interfer	egal equivalents as may l rence, litigation proceedin	be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have her	olication, said invention and said L ecessary or desirable to carry out t	etters Patent and said he proposes thereof.	
Note: An application data sheet (PTC inventive entity, must accompany thi			

Page 1 of 10

NPO#PSM-P0011-USA:0 CUST#PT.AP-2297

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Shih-Ping Lee

Date:

2021,7,26

Signature

Shih-Ping Lee

Page 2 of 10

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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The above-identified application was	made or authorized to be made	by me.		
I believe that I am the original inventorapplication.	or or an original joint inventor of a	claimed invention in the	Э	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri				
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		00), the receipt of which i	is hereby	
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.				
I hereby covenant that no assignmer entered into which would conflict with		ice has been or will be n	nade or	
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.				
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire				

Page 3 of 10

inventive entity, must accompany this form. Use this form for each additional inventor.

NPO#PSM-P0011-USA:0 CUST#PT.AP-2297

LEGAL NAI	ME OF INVENTOR(ASSIC	SNOR)		
Inventor	Tse-Hsien Wu		Date	2021/7/27
Signature	Tse_	ldsien	- .	

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NPO#PSM-P0011-USA-0 CUST#PT.AP-2297

F#NPO-P0002E-US1201 DSB0-110U025409

PATENT

REEL: 057084 FRAME: 0590

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

THROUGH SILICON VIA AND METHOD OF MANUFACTURING THE SAME

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☐ United States application nu	ımber	filed on		or
☐ PCT international application	n number	filed	on	
The above-identified application was	made or authorized to be made t	by me.		
I believe that I am the original invent application.	or or an original joint inventor of a	claimed	invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				
In consideration of the payment by	Powerchip Semiconductor Manufacturing Corporation		naving a postal addı	ress of
NO.18, LI-HSIN RD. 1, HSINCI	HU SCIENCE PARK, HSINCH	HU 300,	Taiwan, R.O.C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good are		00), the re	ceipt of which is her	eby
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified application of substitutes, or extensions thereof, and	nd to any and all improvements w ition and, in and to, all Letters Pate r any continuations, continuation-i	hich are o ent to be n-part, di	disclosed in the obtained for said visions, renewals,	ΞE
I hereby covenant that no assignme entered into which would conflict wit		ice has be	een or will be made	or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exercise.	ntion and said Letters Patent and I estify as to the same in any interfe	legal equi rence, liti	valents as may be	S
representatives any and all papers, maintain, issue and enforce said appequivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention and said L ecessary or desirable to carry out t	etters Pa the propo	tent and said ses thereof.	
Note: An application data sheet (PT inventive entity, must accompany th				

Page 5 of 10

NPO#PSM-P0011-USA:0 CUST#PT.AP-2297

Inventor: Pin-Chieh Huang

Signature: D: 1/2 - Chieh Mugui

EPOWPSM-POOTI-UNA:0 CUST#PT.AP-2297 Page 6 of 10

F#NPO-P0002E-US1201 DSB0-1100025409

PATENT REEL: 057084 FRAME: 0592

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

THROUGH SILICON VIA AND METHOD OF MANUFACTURING THE SAME

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☑ The attached application, or			
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The above-identified application was	made or authorized to be made b	y me.	
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NO.18, LI-HSIN RD. 1, HSINCH	IU SCIENCE PARK, HSINCH	IU 300, Taiwan, R.O.	C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		O), the receipt of which is	hereby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applical invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements wh tion and, in and to, all Letters Pate any continuations, continuation-ir	nich are disclosed in the ent to be obtained for said n-part, divisions, renewals	l S,
I hereby covenant that no assignmer entered into which would conflict with		ce has been or will be ma	de or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent and le stify as to the same in any interfer	egal equivalents as may l rence, litigation proceedin	be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have her	olication, said invention and said L ecessary or desirable to carry out t	etters Patent and said he proposes thereof.	
Note: An application data sheet (PTC inventive entity, must accompany thi			

Page 7 of 10

NPO#PSM-P0011-USA:0 F#NPO-P0002E-US1201 CUST#PT.AP-2297 DSB0-110U025409

LEGAL NAME OF INVENTOR(ASSIGNOR)						
Inventor:	Yu-Hsiang Chien	Date:	8c. P. 140c			
Signature:	Yu Hsiang Chien		****			

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NPO#PSM-P0011-USA:0 CUST#PT.AP-2297

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

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I believe that I am the original invente application.	or or an original joint inventor of a	a claimed inventi	on in the	
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		00), the receipt o	f which is hereby	
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, an	nd to any and all improvements wation and, in and to, all Letters Par any continuations, continuation-	hich are disclose tent to be obtaine in-part, divisions	ed in the ed for said , renewals,	
I hereby covenant that no assignmer entered into which would conflict with		nce has been or	will be made or	
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	olication, said invention and said lecessary or desirable to carry out	Letters Patent ar the proposes the	nd said ereof.	
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Page 9 of 10

NPO#PSM-P0011-USA:0 CUST#PT.AP-2297

inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor	Yeh-Yu Chiang		Date	2021. 7. 2 9.
Signature:	Yeh-Yu	Chiang		

Page 10 of 10

NPO#PSM-P0011-USA:0 CUST#CLAP-2297

RECORDED: 08/04/2021

F#NPG-F0002E-U81301 DSR0-1100025409

PATENT REEL: 057084 FRAME: 0596